

SPECIFICATION FOR APPROVAL

Customer:		
Customer Pa	rt No:	
SHINING Par	t No: SN-NE4040AAYAR-N	
Emitted colo	or: Red	
	Revision History	
Date	Revision History	Prepared
2023.2.22	New Version	A/0
	in the state of th	1

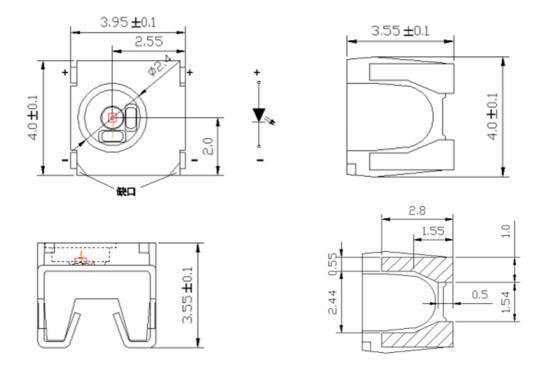
Confirmed By Customer	Approval by	Prepared by	
	Liusan	Shaochengcheng	



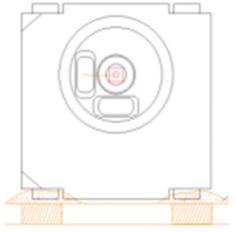
Feature

- Δ 4.0mm×4.0mm×3.55mm
- Δ 0.5W Low Power LED
- Δ $\,$ Suitable for all SMT assembly And solder process.
- △ Moisture sensitivity level: Level 5a
- Δ Vehicle lighting

Package Outline



Pad size



Notes: All dimension units are millimeters.



Absolute maximum ratings at Ta=25 $^{\circ}\!\mathrm{C}$

Parameter	Symbol	Rating	Units
Power Dissipation	Pd	500	mw
Continuous Forward Current	IF	140	mA
Pulsed Forward Current (1/10Duty Cycle, 0.1ms Pulsewidth)	IFP	160	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	4000	V
Operating Temperature	Topr	-30 to +80	${\mathbb C}$
Storage Temperature	Tstg	0-30	$^{\circ}$
Thermal Resistance	Rthj-s	20	°C/W
Junction Temperature	Tj	≤125	$^{\circ}$

Note: 1/10 Duty cycle, 0.1ms pulse width.



Electro-optical characteristics at Ta=25 ℃

Parameter	Symbol	Min	Тур	Max	Unit	Test Condition
Luminous Intensity	IV	18		24	lm	IF=140mA
Viewing Angle	2 θ 1/2	20		40	deg	Note 1
Dominant Wavelength	λd		620-630		nm	IF=140mA
Color rendering index	Ra					
Forward Voltage (R)	VF	2.0		2.4	V	IF=140mA
ReverseCurrent	IR			10	μА	VR=5V

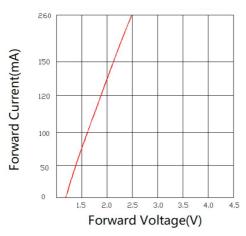
Note

- 1. 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value
- 2. The above luminous flux measurement allowance tolerance is $\pm 15\%$.
- 3. The above Color Rendering Index measurement allowance tolerance is ± 2
- 4. The above forward voltage measurement allowance tolerance is $\pm 0.1 \text{V}$



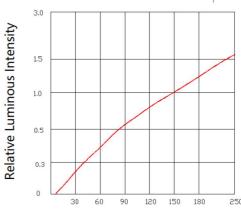
Typical optical characteristics curves

Forward Voltage VS.Forward Current

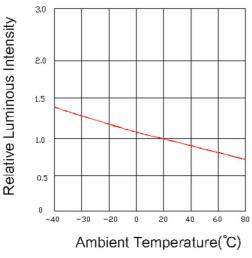


Ambient Temperature VS.Relative Intensity

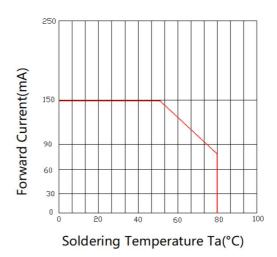
Forward Current VS.Relative Intensity



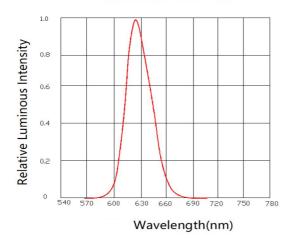
Forward Current(mA) Soldering Temperature VS.Forward Current

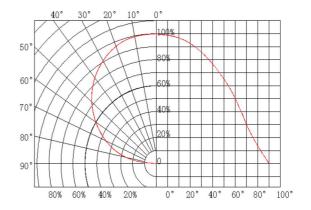


Relative Spectral emission



Radiation diagram







Reliability Test Items And Conditions

Test Items	Ref. Standard	Test Condition	Time	Quantity	Ac/Re
Reflow	JESD22-A113	Temp:260 ℃ max T=10 sec	3 times	30PCS	0/1
Temperature Cycle	JESD22-A104	$-40^{\circ}\mathrm{C}\pm5^{\circ}\mathrm{C}$ $30\mathrm{min}$ ↑ ↓ 5 min $120^{\circ}\mathrm{C}\pm5^{\circ}\mathrm{C}$ $30\mathrm{min}$	100Cycles	200PCS	0/1
Power Temperature Cycling	JESD22-A105	$-40^{\circ}\!$	1000H	30PCS	0/1
High Humidity Heat Life Test	JESD22-A101	Ta=85 ℃ RH=85% IF=5mA/10mA	1000H	30PCS	0/1
High Temperature Operating	JESD22-A108	Ta=25°C ±5°C IF=140mA	- 1000H	30PCS	- 0/1
Life		Ta=85°C ±5°C IF=140mA		30PCS	
High Temperature Storage	Tested with standard	Temp:85 °C ± 5 °C	1000H	22PCS	0/1
Low Temperature Storage	IEC60068-2-1: 2007	Temp:-30 °C ±5 °C	1000H	22PCS	0/1
Life Test	Tested with standard	Ta=25℃±5℃ IF=140mA	1000H	22PCS	0/1

Failure Criteria

Test Items	Symbol	Test Condition	Failure Criteria		
rest items	Symbol	rest containon	MIN	MAX	
forward voltage	VF	IF=140mA		U.S.L*)x1.1	
reverse current	IR	VR = 5V		10uA	
light quantity	lm	IF=140mA	L.S.L*)x0.7		

U.S.L: Upper Specification Limit

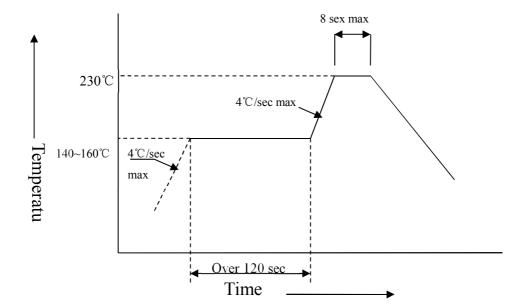
L.S.L: Lower Specification Limit



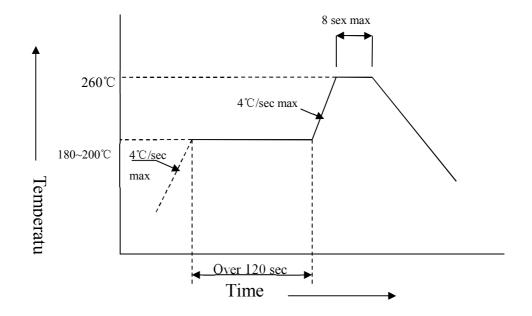
SMT Reflow Soldering Instructions SMT

Reflow Soldering Instructions

Number of reflow process shall be less than 1 times Lead Solder



Lead-Free Solder



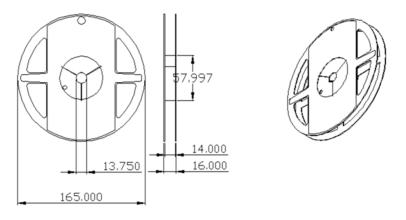


Packing

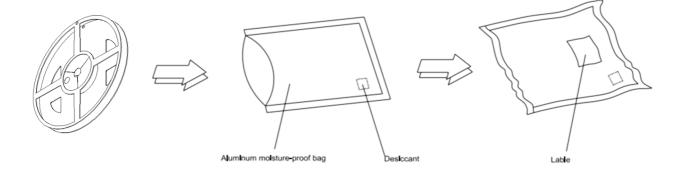
Tape Specifications (Units : mm) Packing unit2004PCS/reel

Adhesion Strength of Cover Tape: Adhesion strength to be 0.1 - 0.7N when the cover tape is turned off from the carrier at 10° angle to be the carrier tape.

Reel Dimensions



Moisture Resistant Packaging





SMD LED Instruction Manual

Dear partners!

Thank you for your trust and support to our company. In order to enhance your understanding of the product characteristics of our company, it is convenient for you to grasp the characteristics of its use during use, to minimize or avoid unnecessary product damage or performance mismatch caused by human factors. Specifically here

1. Material confirmation

Please check the package for leaks, other damage, and check if the label matches your company's requirements. If you find an abnormality, please contact us in time.

2. Unopened smd led storage

The unopened smd led should not be stored for a long time as much as possible, because the storage environment is not easy to control. You can choose a recent delivery based on your order. The storage environment is best to choose moisture-proof cabinet, the temperature is about 30 degrees, the humidity is below 60%, in this case RGB products can be stored for 30 days, white light products can be stored for 60 days. Regardless of whether the storage time is exceeded or not, be sure to perform the first test before production. If you find a problem, please contact us as soon as possible.

3. Precautions after unpacking

After receiving the smd led of our company, please arrange the production as soon as possible. Due to the different storage environments of each warehouse, it is not recommended to make large quantities of stocks. Please use up the product within 24 hours after opening the package. It is recommended to perform 60 degree low temperature baking for 12-24 hours before use.

4. It is not recommended to mix different batches of smd led

Test before the production according to the first inspection standard. If you find any abnormality in the smd led, please contact us. Please do not mix different batches of smd led during the production process. If you can't avoid it, you need to use the leds of the previous batch. Please confirm the package is normal, and then confirm the first piece. Finally, the products produced by this batch of smd led are separately distinguished.

5. It is not recommended to store the smd led after unpacking.

Please accurately calculate the demand for the production line. If storage is required, it is recommended to store in a 60 degree oven. In the production process, please fill in the reflow soldering after the patch is completed, and the reflow soldering is not repeatable.

- Reflow soldering. Check the ESD protection measures during soldering and assembly.
- 7. smd led for outdoor application, the finished product design is to use a cover lens as much as possible, and then potting seal.

It is not recommended to seal directly on the surface of the lamp. The potting glue should try to choose a gluewith low permeability and oxygen permeability and good adhesion to aluminum. The controller's negative pressure should be minimized.

8. Finished luminaires that have been installed outdoors.

If the luminaires cannot be used in time after commissioning, please pay attention to the timing aging. Please use a small current to illuminate all the chips in the early stage of aging. Do not scan the program. After aging for two hours, the current is gradually amplified, do not scan the program, and often aging for 4 hours once a month. In the initial stage of use, please adjust the speed of the controller to the slowest and the color conversion speed is the slowest.